

## LM837 Low Noise Quad Operational Amplifier

Check for Samples: [LM837](#)

### FEATURES

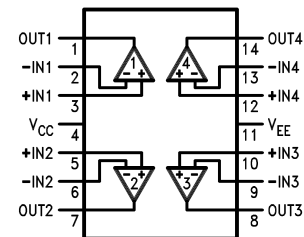
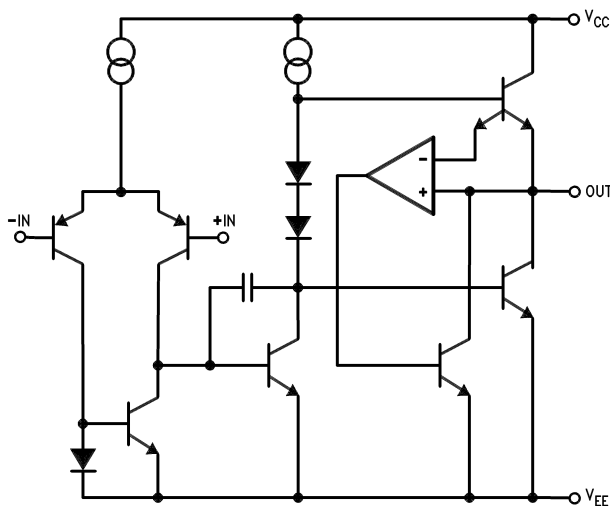
- **High Slew Rate** 10 V/ $\mu$ s (typ); 8 V/ $\mu$ s (min)
- **Wide Gain Bandwidth Product** 25 MHz (typ); 15 MHz (min)
- **Power Bandwidth** 200 kHz (typ)
- **High Output Current**  $\pm 40$  mA
- **Excellent Output Drive Performance**  $>600\Omega$
- **Low Input Noise Voltage** 4.5 nV/ $\sqrt{\text{Hz}}$
- **Low Total Harmonic Distortion** 0.0015%
- **Low Offset Voltage** 0.3 mV

### DESCRIPTION

The LM837 is a quad operational amplifier designed for low noise, high speed and wide bandwidth performance. It has a new type of output stage which can drive a 600 $\Omega$  load, making it ideal for almost all digital audio, graphic equalizer, preamplifiers, and professional audio applications. Its high performance characteristics also make it suitable for instrumentation applications where low noise is the key consideration.

The LM837 is internally compensated for unity gain operation. It is pin compatible with most other standard quad op amps and can therefore be used to upgrade existing systems with little or no change.

### Schematic and Connection Diagrams



**Figure 1. PDIP Package  
Top View  
See Package Number  
D0014A or NFF0014A**



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These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

## ABSOLUTE MAXIMUM RATINGS<sup>(1)(2)</sup>

Supply Voltage, $V_{CC}/V_{EE}$	±18V
Differential Input Voltage, $V_{ID}^{(3)}$	±30V
Common Mode Input Voltage, $V_{IC}^{(3)}$	±15V
Power Dissipation, $P_D^{(4)}$	1.2W (N) 830 mW (M)
Operating Temperature Range, $T_{OPR}$	–40°C to +85°C
Storage Temperature Range, $T_{STG}$	–60°C to +150°C
Soldering Information PDIP Package Soldering (10 seconds)	260°C
SOIC Package Vapor Phase (60 seconds)	215°C
Infrared (15 seconds)	220°C
ESD rating to be determined.	
See <a href="http://www.ti.com">http://www.ti.com</a> for other methods of soldering surface mount devices.	

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not ensure specific performance limits. Electrical Characteristics state DC and AC electrical specifications under particular test conditions which ensure specific performance limits. This assumes that the device is within the Operating Ratings. Specifications are not specified for parameters where no limit is given, however, the typical value is a good indication of device performance.
- (2) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/Distributors for availability and specifications.
- (3) Unless otherwise specified the absolute maximum input voltage is equal to the power supply voltage.
- (4) For operation at ambient temperatures above 25°C, the device must be derated based on a 150°C maximum junction temperature and a thermal resistance, junction to ambient, as follows: LM837N, 90°C/W; LM837M, 150°C/W.

## DC ELECTRICAL CHARACTERISTICS

$T_A = 25^\circ\text{C}$ ,  $V_S = \pm 15\text{V}$

Symbol	Parameter	Condition	Min	Typ	Max	Units
$V_{OS}$	Input Offset Voltage	$R_S = 50\Omega$		0.3	5	mV
$I_{OS}$	Input Offset Current			10	200	nA
$I_B$	Input Bias Current			500	1000	nA
$A_V$	Large Signal Voltage Gain	$R_L = 2\text{ k}\Omega$ , $V_{OUT} = \pm 10\text{V}$	90	110		dB
$V_{OM}$	Output Voltage Swing	$R_L = 2\text{ k}\Omega$	±12	±13.5		V
		$R_L = 600\Omega$	±10	±12.5		V
$V_{CM}$	Common Mode Input Voltage		±12	±14.0		V
CMRR	Common Mode Rejection Ratio	$V_{IN} = \pm 12\text{V}$	80	100		dB
PSRR	Power Supply Rejection Ratio	$V_S = 15 \sim 5$ , $-15 \sim -5$	80	100		dB
$I_S$	Power Supply Current	$R_L = \infty$ , Four Amps		10	15	mA

## AC ELECTRICAL CHARACTERISTICS

$T_A = 25^\circ\text{C}$ ,  $V_S = \pm 15\text{V}$

Symbol	Parameter	Condition	Min	Typ	Max	Units
SR	Slew Rate	$R_L = 600\Omega$	8	10		V/μs
GBW	Gain Bandwidth Product	$f = 100\text{ kHz}$ , $R_L = 600\Omega$	15	25		MHz

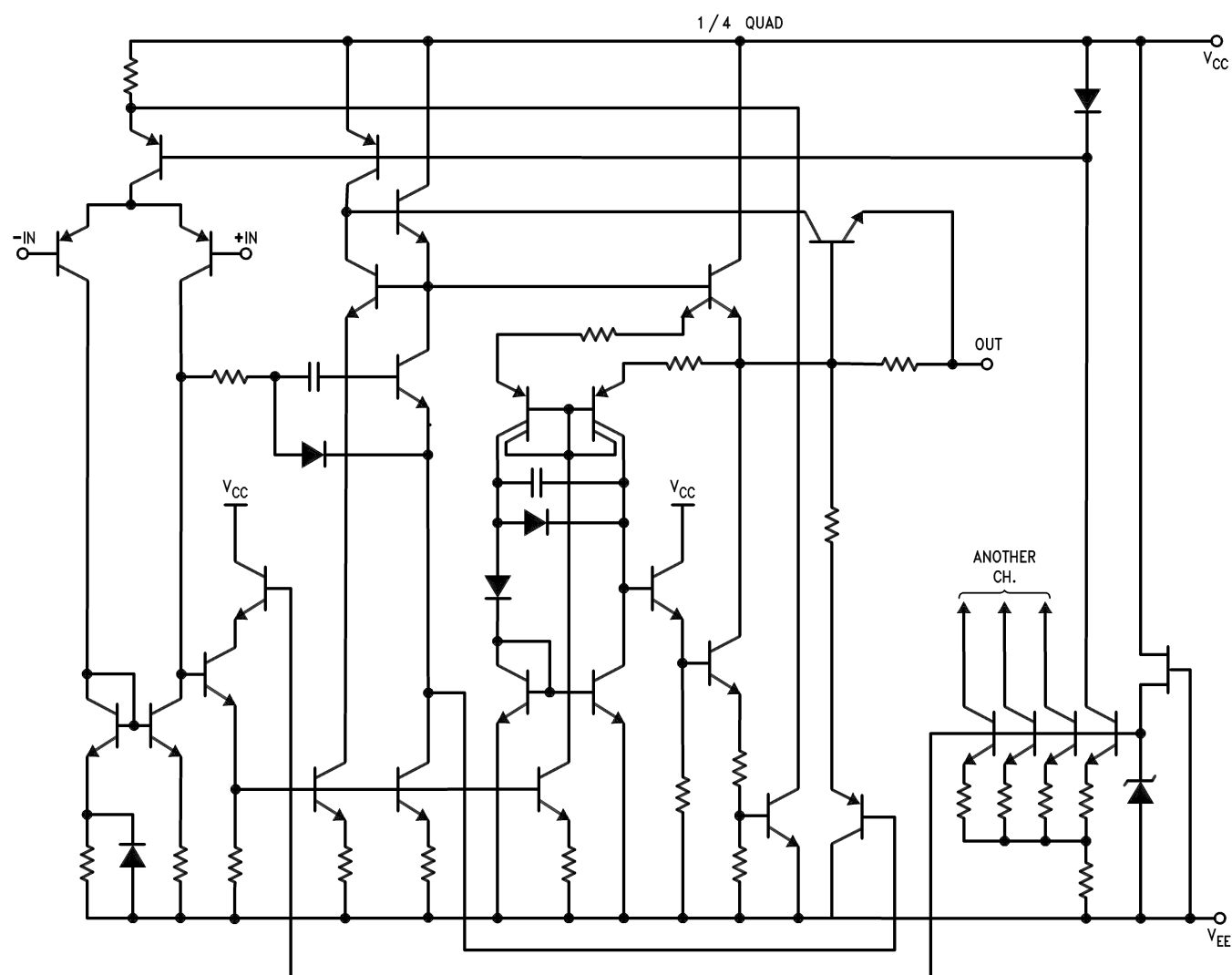
## DESIGN ELECTRICAL CHARACTERISTICS

 $T_A = 25^\circ\text{C}$ ,  $V_S = \pm 15\text{V}$  <sup>(1)</sup>

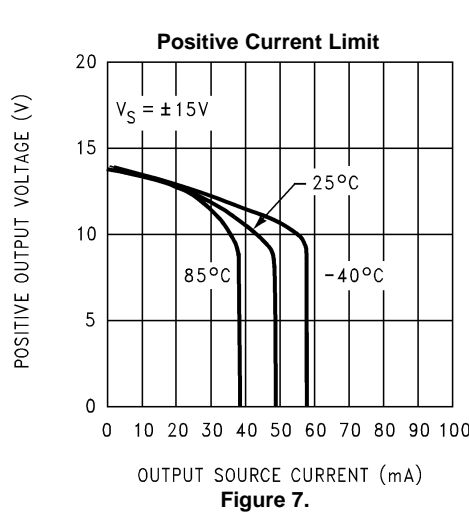
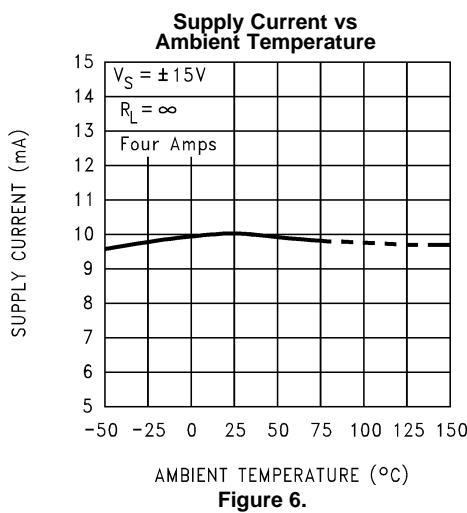
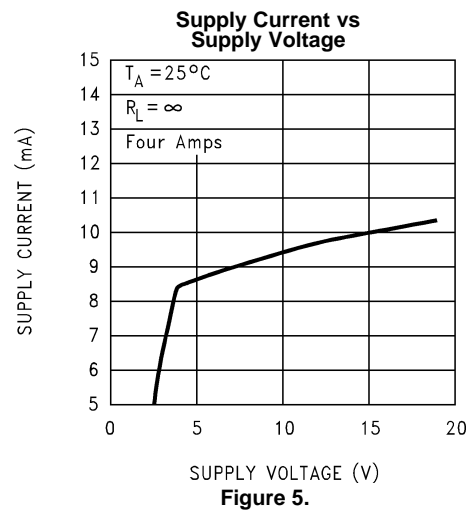
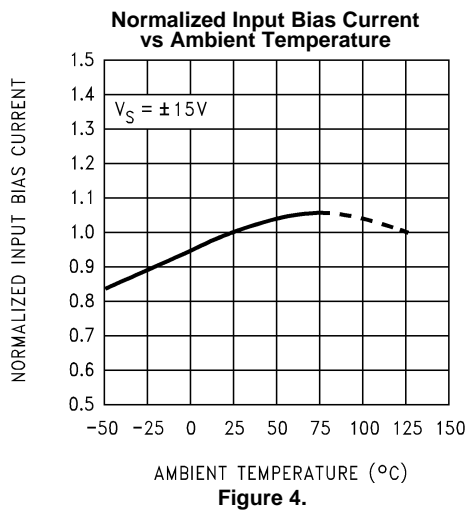
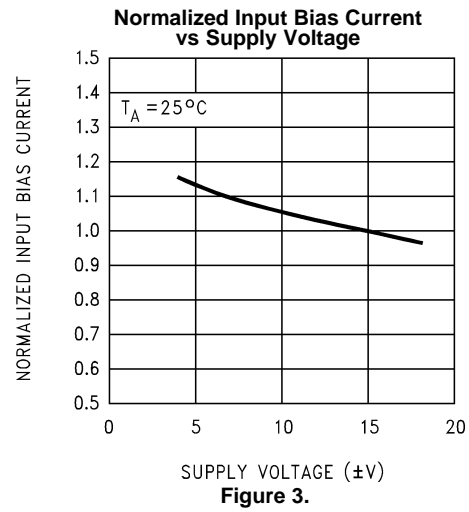
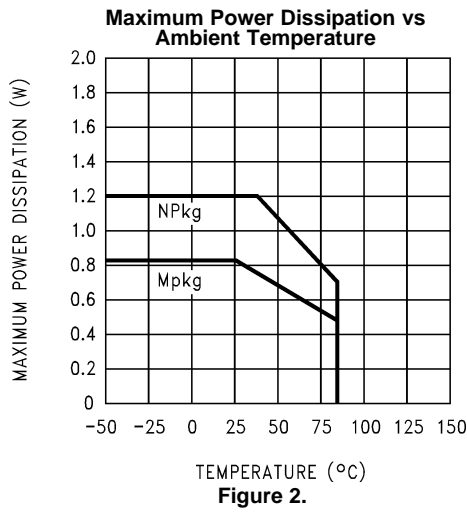
Symbol	Parameter	Condition	Min	Typ	Max	Units
PBW	Power Bandwidth	$V_O = 25\text{ V}_{P-P}$ , $R_L = 600\Omega$ , THD < 1%		200		kHz
$e_{n1}$	Equivalent Input Noise Voltage	JIS A, $R_S = 100\Omega$		0.5		$\mu\text{V}$
$e_{n2}$	Equivalent Input Noise Voltage	$f = 1\text{ kHz}$		4.5		$\text{nV}/\sqrt{\text{Hz}}$
$i_n$	Equivalent Input Noise Current	$f = 1\text{ kHz}$		0.7		$\text{pA}/\sqrt{\text{Hz}}$
THD	Total Harmonic Distortion	$A_V = 1$ , $V_{OUT} = 3\text{ V}_{rms}$ , $f = 20 \sim 20\text{ kHz}$ , $R_L = 600\Omega$		0.0015		%
$f_U$	Zero Cross Frequency	Open Loop		12		MHz
$\Phi_m$	Phase Margin	Open Loop		45		deg
	Input-Referred Crosstalk	$f = 20 \sim 20\text{ kHz}$		-120		dB
$\Delta V_{OS}/\Delta T$	Average TC of Input Offset Voltage			2		$\mu\text{V}/^\circ\text{C}$

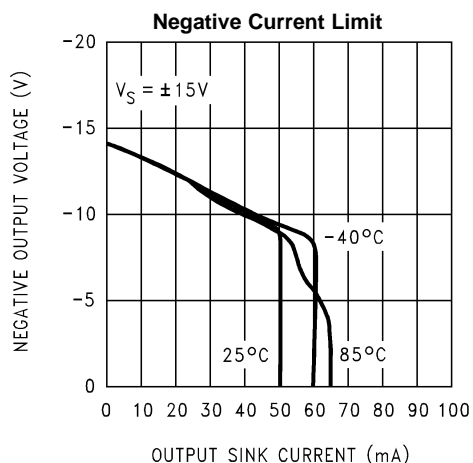
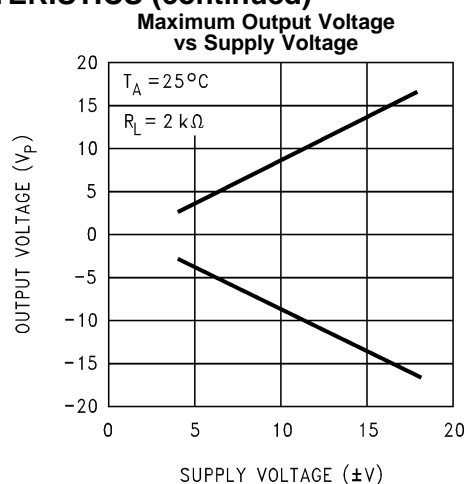
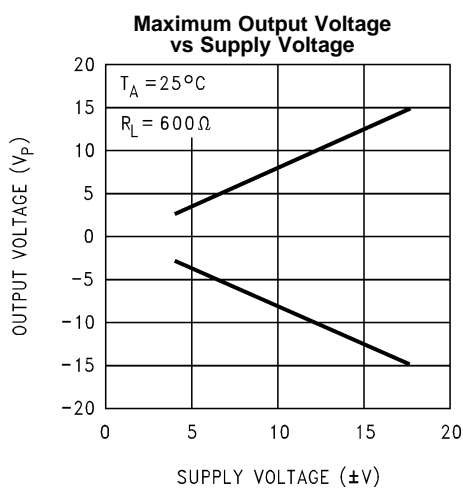
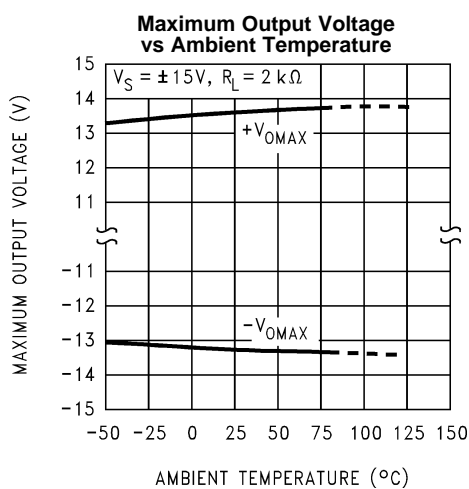
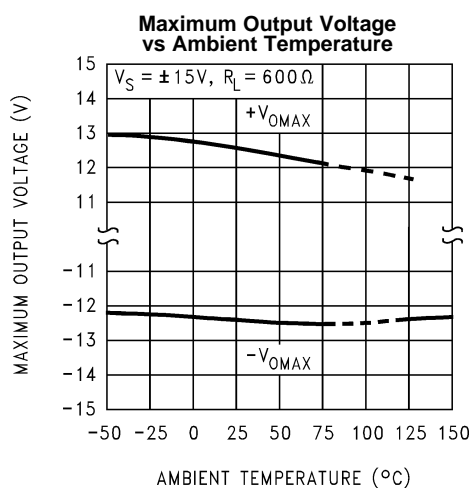
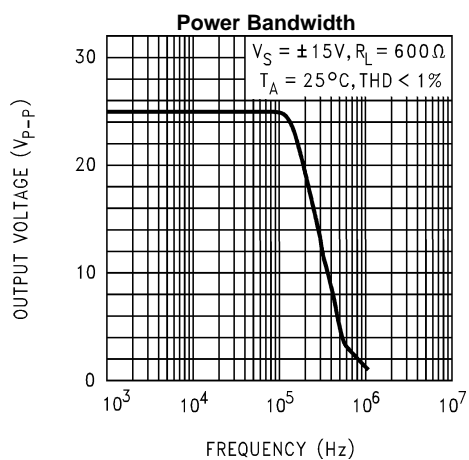
(1) The following parameters are not tested or ensured.

## DETAILED SCHEMATIC

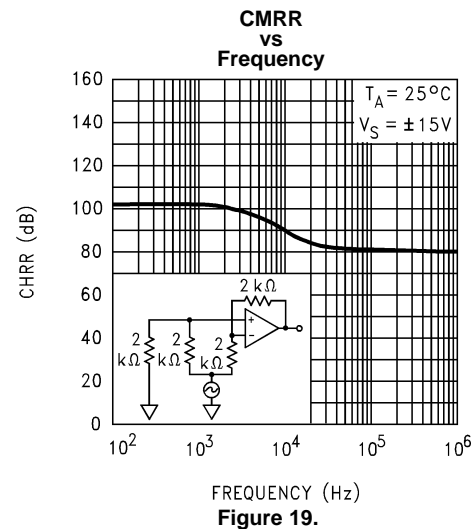
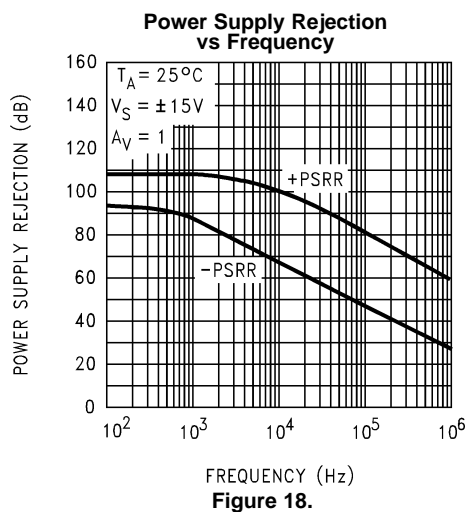
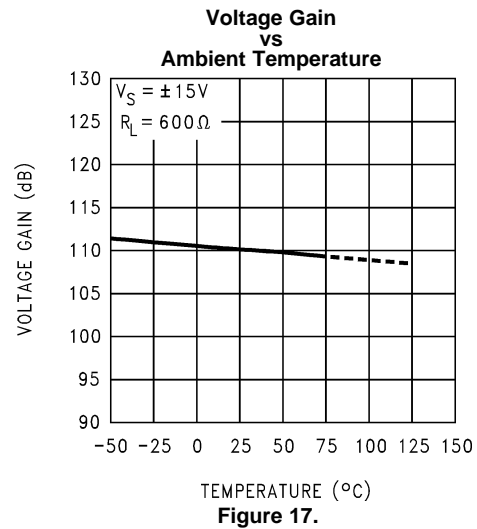
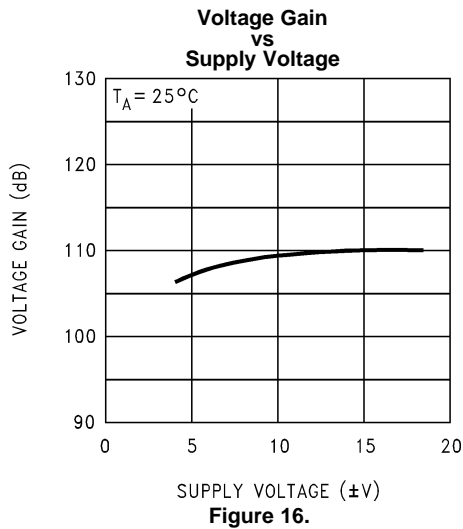
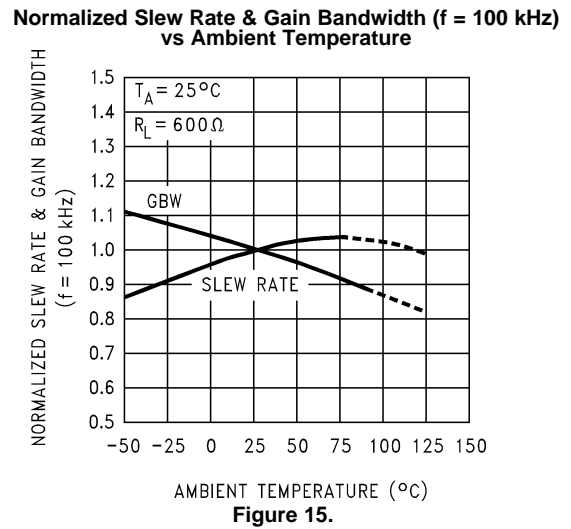
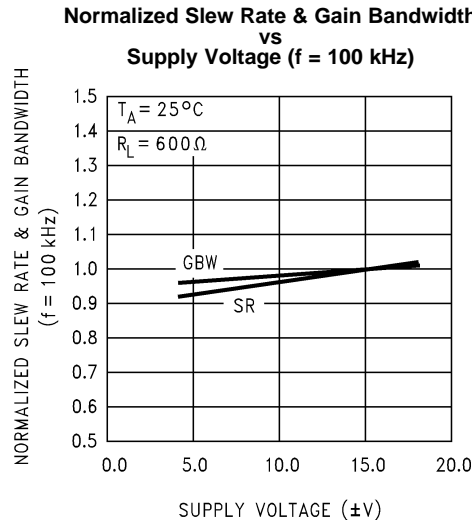


## TYPICAL PERFORMANCE CHARACTERISTICS



**TYPICAL PERFORMANCE CHARACTERISTICS (continued)****Figure 8.****Figure 9.****Figure 10.****Figure 11.****Figure 12.****Figure 13.**

## TYPICAL PERFORMANCE CHARACTERISTICS (continued)



## TYPICAL PERFORMANCE CHARACTERISTICS (continued)

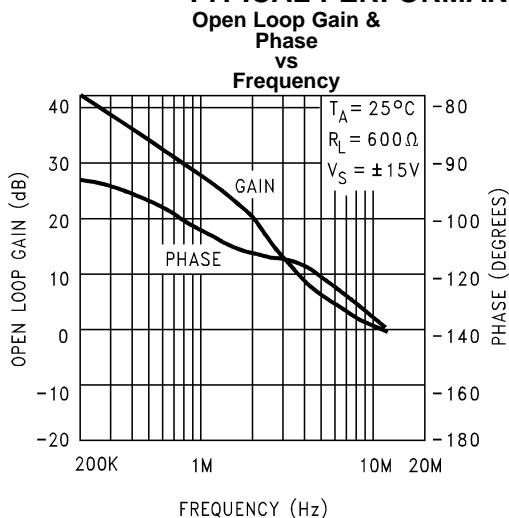


Figure 20.

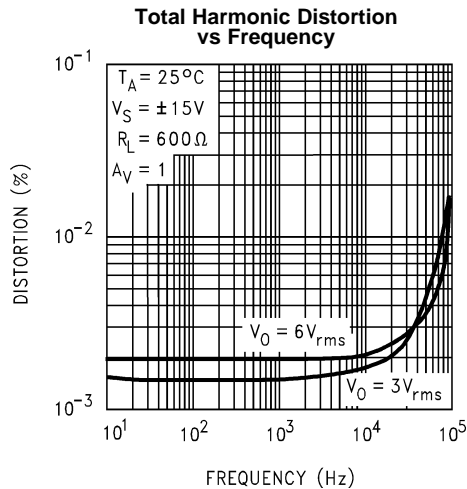


Figure 21.

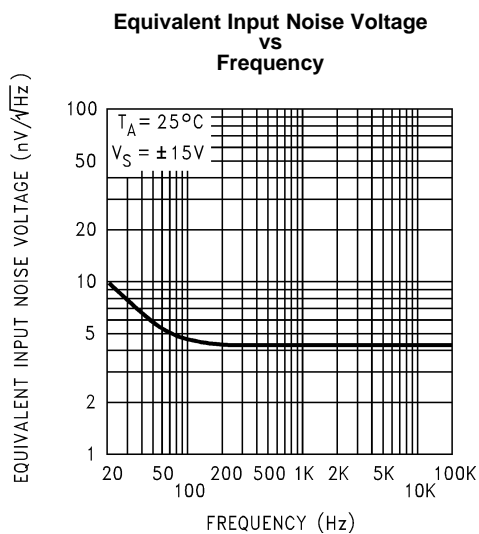


Figure 22.

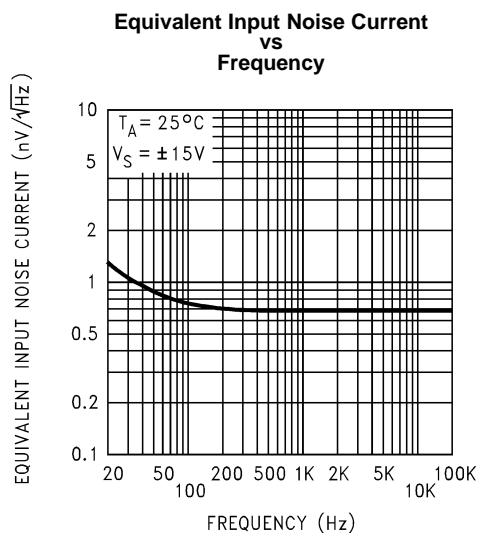


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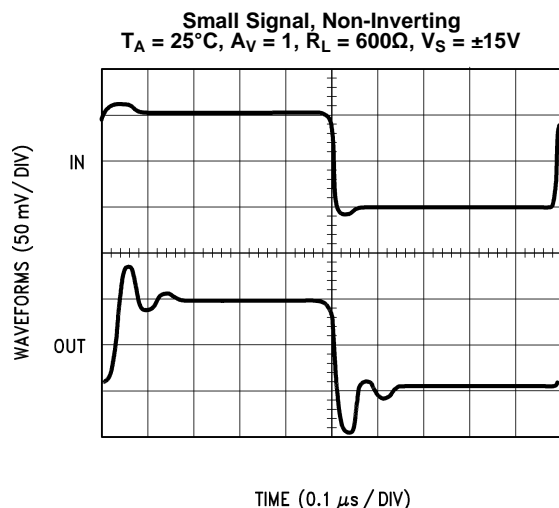


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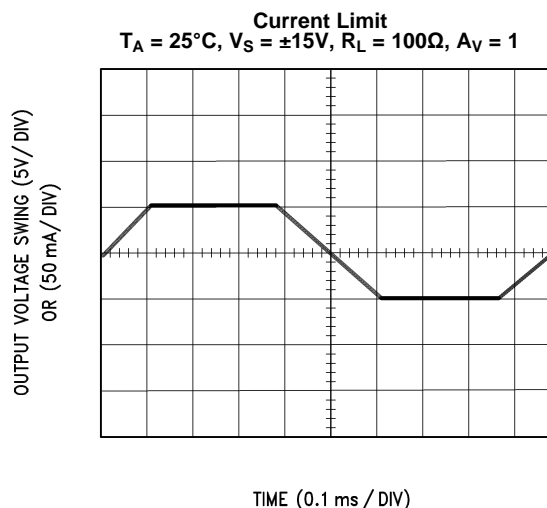
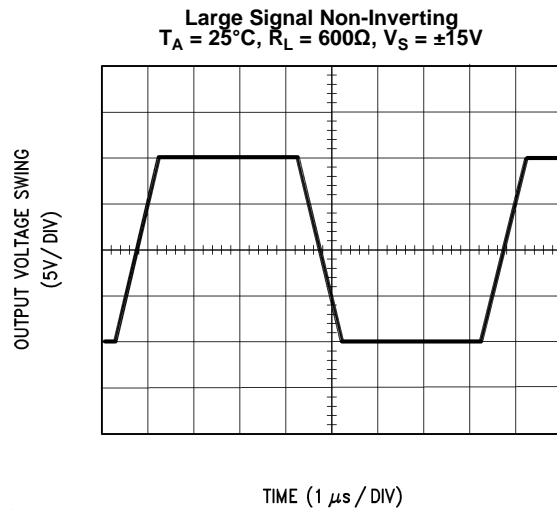


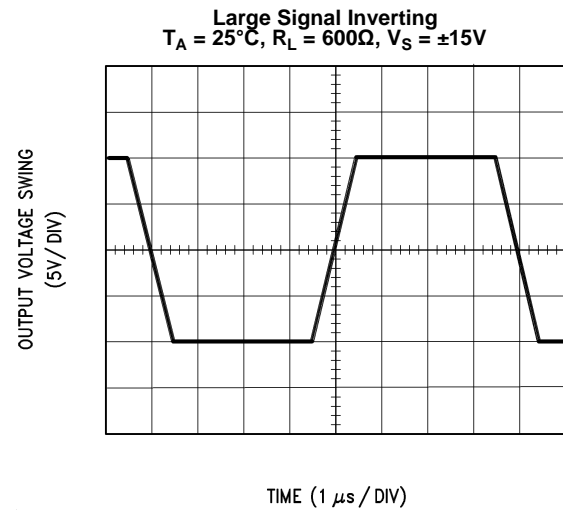
Figure 25.



## TYPICAL PERFORMANCE CHARACTERISTICS (continued)



**Figure 26.**



**Figure 27.**

REVISION HISTORY

Changes from Revision B (March 2013) to Revision C	Page
• Changed layout of National Data Sheet to TI format .....	<a href="#">5</a>

## PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LM837M	ACTIVE	SOIC	D	14	55	TBD	Call TI	Call TI	-40 to 85	LM837M	<a href="#">Samples</a>
LM837M/NOPB	ACTIVE	SOIC	D	14	55	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	LM837M	<a href="#">Samples</a>
LM837MX	ACTIVE	SOIC	D	14	2500	TBD	Call TI	Call TI	-40 to 85	LM837M	<a href="#">Samples</a>
LM837MX/NOPB	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	LM837M	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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**TAPE AND REEL INFORMATION**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM837MX	SOIC	D	14	2500	330.0	16.4	6.5	9.35	2.3	8.0	16.0	Q1
LM837MX/NOPB	SOIC	D	14	2500	330.0	16.4	6.5	9.35	2.3	8.0	16.0	Q1

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM837MX	SOIC	D	14	2500	367.0	367.0	35.0
LM837MX/NOPB	SOIC	D	14	2500	367.0	367.0	35.0

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.

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Data Converters	<a href="http://dataconverter.ti.com">dataconverter.ti.com</a>
DLP® Products	<a href="http://www.dlp.com">www.dlp.com</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>
Clocks and Timers	<a href="http://www.ti.com/clocks">www.ti.com/clocks</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>
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RFID	<a href="http://www.ti-rfid.com">www.ti-rfid.com</a>
OMAP Applications Processors	<a href="http://www.ti.com/omap">www.ti.com/omap</a>
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### Applications

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Communications and Telecom	<a href="http://www.ti.com/communications">www.ti.com/communications</a>
Computers and Peripherals	<a href="http://www.ti.com/computers">www.ti.com/computers</a>
Consumer Electronics	<a href="http://www.ti.com/consumer-apps">www.ti.com/consumer-apps</a>
Energy and Lighting	<a href="http://www.ti.com/energy">www.ti.com/energy</a>
Industrial	<a href="http://www.ti.com/industrial">www.ti.com/industrial</a>
Medical	<a href="http://www.ti.com/medical">www.ti.com/medical</a>
Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
Space, Avionics and Defense	<a href="http://www.ti.com/space-avionics-defense">www.ti.com/space-avionics-defense</a>
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